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ELECTRONICS

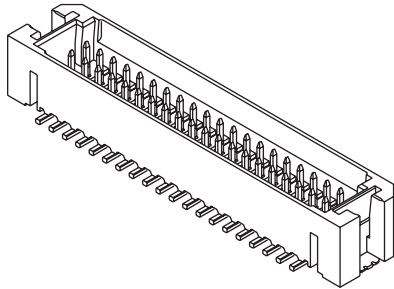
www.Jameco.com ♦ 1-800-831-4242

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Jameco Part Number 1932109

1.25mm (.049") Pitch Pico-Gold™ Wire-to-Board Header

53505
Dual Row
Vertical, SMT



Features and Benefits
 ■ Sizes: 20, 30 and 40 circuits
 ■ Mated height only 5.9mm

Reference Information
 Packaging: Embossed tape
 Mates With: 51127
 Designed In: Millimeters

Electrical
 Voltage: 125V
 Current: 1.0A
 Contact Resistance: 20 milliohms max.
 Dielectric Withstanding Voltage: 250V AC
 Insulation Resistance: 100 Megohms min.

Physical
 Housing: Glass-filled PPA, UL 94V-0
 Contact: Phosphor Bronze
 Contact Plating: Gold over Nickel
 Solder Tail Plating: Tin over Nickel
 Solder Tabs: Phosphor Bronze, Tin over Nickel plating
 Operating Temperature: -40 to +85°C

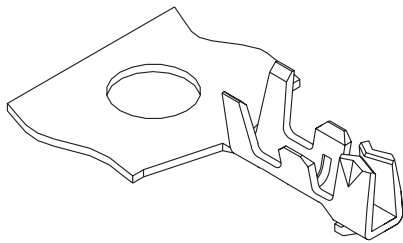
Circuits	Order No.	Carrier Tape Width	Lead-free
20	53505-2071	32.00 (1.259)	Yes
30	53505-3071	44.00 (1.732)	
40	53505-4071		

Note: Contact Molex for for embossed tape specifications

www.molex.com/customer.html?seriesNumber=53505

1.25mm (.049") Pitch PicoBlade™ Wire-to-Board and Wire-to-Wire Crimp Terminal

50079/50058
Female



Features and Benefits
 ■ Locking tang for secure housing retention

Reference Information
 Packaging: Reel or bag
 Use With: 51021
 Designed In: Millimeters

Electrical
 Voltage: 125V
 Current: 1.0A (32 AWG—0.8A)
 Contact Resistance: 20 milliohms max.
 Dielectric Withstanding Voltage: 250V AC/1 min.
 Insulation Resistance: 100 Megohms min.

Physical
 Contact: Phosphor Bronze
 Plating: Tin
 Wire Range: 26 to 28 AWG—50079
 28 to 32 AWG—50058
 Insulation Range: 50058—1.00mm dia. max.
 50079—1.04mm dia. max.
 Strip Length: 1.40 to 1.90mm

Order No.	Wire Range AWG	Terminal	Lead-free
50079-8000	26 - 28	Reel	Yes
50058-8000	28 - 32		
50079-8100	26 - 28	Bag	
50058-8100	28 - 32		



PRODUCT SPECIFICATION



LANGUAGE

JAPANESE
ENGLISH

【3. 定格及び適用電線 RATINGS AND APPLICABLE WIRES】

項目 Item	規 格 Standard	
最大許容電圧 Rated Voltage(MAX.)	1 2 5 V	
最大許容電流 及び適用電線 Rated Current (MAX.) and Applicable wires	AWG # 2 6	1 A
	AWG # 2 8	1 A
	AWG # 3 0	1 A
	AWG # 3 2	0 . 8 A
使用温度範囲 Ambient temperature Range	- 4 0 °C ~ + 8 5 °C *1	

[AC (実効値 rms) / DC]

被覆外径 : 1.0mm MAX.
Insulation O.D.

*1 : 通電による温度上昇分も含む。

Including terminal temperature rise.

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AJ2003-0019
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'02/07/05

REV.

DESCRIPTION

TITLE:

1.25mm WIRE TO BOARD
SMT CONNECTOR**製品仕様書**THIS DOCUMENT CONTAINS INFORMATION THAT IS PROPRIETARY TO
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DOCUMENT NUMBER

PS-51021-022

FILENAME

PS51021022.lwp

SHEET

2 OF 12

ES-4000-3996 REV. A SHEET 4 95/MAR/10 EC U5-0926 DCBRD03.LWP

W to B 1

EN-37-1(019)



PRODUCT SPECIFICATION



LANGUAGE

JAPANESE
ENGLISH

【 4. 性能 PERFORMANCE 】

4 - 1. 電気的性能 Electrical Performance

項目 Item		条件 Test Condition	規格 Requirement
4-1-1	接触抵抗 Contact Resistance	コネクタを嵌合させ、開放電圧 20mV 以下、 短絡電流 10mA にて測定する。 (JIS C5402 5.4) Mate connectors,measure by dry circuit, 20mV MAX., 10mA. (JIS C5402 5.4)	20 milliohm MAX.
4-1-2	絶縁抵抗 Insulation Resistance	コネクタを嵌合させ、隣接するターミナル間 及びタ - ミナル、アース間に、DC 500V を 印加し測定する。 (JIS C5402 5.2/MIL-STD-202 試験法 302) Mate connectors, apply 500V DC between adjacent terminal or ground. (JIS C5402 5.2/MIL-STD-202 Method 302)	100 Megohm MIN.
4-1-3	耐電圧 Dielectric Strength	コネクタを嵌合させ、隣接するタ - ミナル間 及びタ - ミナル、アース間に、AC(rms) 250V (実効値) を 1分間 印加する。 (JIS C5402 5.1/MIL-STD-202 試験法 301) Mate connectors, apply 250V AC(rms) for 1 minute between adjacent terminal or ground.(JIS C5402 5.1/MIL-STD-202 Method 301)	異状なきこと No Breakdown
4-1-4	圧着部接触抵抗 Contact Resistance on Crimped Portion	タ - ミナルに適合電線を圧着し、開放電圧 20mV 以下、短絡電流 10mA にて測定する。 Crimp the applicable wire on to the terminal, measure by dry circuit, 20mV MAX., 10mA.	5 milliohm MAX.

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3 OF 12



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4 - 2. 機械的性能 Mechanical Performance

項目 Item		条件 Test Condition		規格 Requirement
4-2-1	挿入力及び抜去力 Insertion and Withdrawal Force	毎分 25±3mm の速さで挿入、抜去を行なう。 Insert and withdraw connectors at the speed rate of 25±3mm/minute.		第 7 項 参 照 Refer to paragraph 7.
4-2-2	圧着部引張り強度 Crimping Pull Out Force	圧着されたタ - ミナルを治具に固定し、電線を軸方向に毎分 25 ± 3mm の速さで引張る。 (JIS C5402 6.8) Fix the crimped terminal, apply axial pull out force on the wire at the speed rate of 25±3mm/minute. (JIS C5402 6.8)	AWG.#26	9.8N {1.0kgf} MIN.
			AWG.#28	9.8N {1.0kgf} MIN.
			AWG.#30	4.9N {0.5kgf} MIN.
			AWG.#32	3.0N {0.3kgf} MIN.
4-2-3	ターミナル挿入力 Terminal Insertion Force	圧着されたターミナルをハウジングに挿入する。 Insert the crimped terminal into the housing.		4.9N {0.5kgf} MAX.
4-2-4	ターミナル保持力 Terminal/Housing Retention Force	圧着されたターミナルをハウジングに装着し、電線を軸方向に毎分 25±3mm の速さで引張る。 Apply axial pull out force at the speed rate of 25±3 mm/minute on the terminal assembled in the housing.		4.9N {0.5kgf} MIN.

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4 OF 12



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項目 Item	条件 Test Condition	規格 Requirement
4-2-5 ピン保持力 Pin Retention Force	毎分 25±3mm の速さで ピンを軸方向に押す。 Apply axial push force at the speed rate of 25±3mm /minute.	4.9N {0.5kgf} MIN.

4 - 3. その他 Environmental Performance Others

項目 Item	条件 Test Condition	規格 Requirement	
4-3-1 繰返し挿抜 Repeated Insertion/ Withdrawal	1分間 10回 以下の速さで挿入、 抜去を 30回 繰返す。 When mated up to 30 cycles repeatedly by the rate of 10 cycles per minute.	接触抵抗 Contact Resis- tance	40 milliohm MAX.
4-3-2 温度上昇 Temperature Rise	コネクタを嵌合させ、最大許容電流 を通電し、コネクタの温度上昇分を 測定する。(UL 498) Carrying rated current load. (UL 498)	温度上昇 Tempera- ture rise	30 °C MAX.
4-3-3 耐振動性 Vibration	DC 1mA 通電状態にて、嵌合軸を含む 互いに垂直な 3方向 に掃引割合 10~55~10 Hz/分 全振幅 1.5mm の振動を各 2時間 加える。 (MIL-STD-202 試験法 201) Amplitude: 1.5mm P-P Sweep time: 10~55~10 Hz in 1 minute Duration: 2 hours in each X.Y.Z. axes (MIL-STD-202 Method 201)	外観 Appearance	異常なきこと No Damage
		接触抵抗 Contact Resistance	40 milliohm MAX.
		瞬断 Dis- continuity	1 microsecond MAX.

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PS-51021-022	PS51021022.lwp	5 OF 12



PRODUCT SPECIFICATION



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項目 Item		条件 Test Condition	規格 Requirement	
4-3-4	耐衝撃性 Shock	DC 1mA 通電状態にて、嵌合軸を含む互いに垂直な 6方向 に 490m/s ² {50G} の衝撃を各 3回 加える。 (JIS C0041/MIL-STD-202 試験法213) 490m/s ² {50G}, 3 strokes in each X.Y.Z. axes. (JIS C0041/MIL-STD-202 Method 213)	外観 Appearance	異常なきこと No Damage
			接触抵抗 Contact Resistance	40 milliohm MAX.
			瞬断 Dis-continuity	1 microsecond MAX.
4-3-5	耐熱性 Heat Resistance	コネクタを嵌合させ、85±2 °C の雰囲気中に 96時間 放置後取り出し、1 ~ 2 時間 室温に放置する。 (JIS C0021/MIL-STD-202 試験法108) 85±2 °C, 96 hours (JIS C0021/MIL-STD-202 Method 108)	外観 Appearance	異常なきこと No Damage
			接触抵抗 Contact Resistance	40 milliohm MAX.
4-3-6	耐寒性 Cold Resistance	コネクタを嵌合させ、-40±3 °C の雰囲気中に 96時間 放置後取り出し、1 ~ 2時間 室温に放置する。 (JIS C0020) -40±3 °C, 96 hours (JIS C0020)	外観 Appearance	異常なきこと No Damage
			接触抵抗 Contact Resistance	40 milliohm MAX.

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PS51021022.lwp

SHEET

6 OF 12



PRODUCT SPECIFICATION



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項目 Item		条件 Test Condition	規格 Requirement	
4-3-7	耐湿性 Humidity	コネクタを嵌合させ、60±2 °C、 相対湿度 90 ~ 95%の雰囲気中に 96時間 放置後取り出し、 1 ~ 2時間 室温に放置する。 (JIS C0022/MIL-STD-202 試験法103) Temperature: 60±2 °C Relative Humidity: 90 ~ 95% Duration: 96 hours (JIS C0022/MIL-STD-202 Method 103)	外観 Appearance	異常なきこと No Damage
			接触抵抗 Contact Resistance	40 milliohm MAX.
			耐電圧 Dielectric Strength	4-1-3項満足のこと Must meet 4-1-3
			絶縁抵抗 Insulation Resistance	10 Megohm MIN.
4-3-8	温度サイクル Temperature Cycling	コネクタを嵌合させ、- 55 °C に 30分、+ 105 °C に 30分 これを 1サイクルとし、5サイクル 繰返す。 但し、温度移行時間は5分以内とする。 試験後 1 ~ 2時間 室温に放置する。 (JIS C0025) 5 cycles of: a) - 55 °C 30 minutes b) +105 °C 30 minutes (JIS C0025)	外観 Appearance	異常なきこと No Damage
			接触抵抗 Contact Resistance	40 milliohm MAX.

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FILENAME

PS51021022.lwp

SHEET

7 OF 12



PRODUCT SPECIFICATION



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項目 Item		条件 Test Condition	規格 Requirement	
4-3-9	塩水噴霧 Salt Spray	コネクタを嵌合させ、35±2 °Cにて 5±1% 重量比の塩水を 48±4時間 噴霧し、試験後常温で水洗いした後、 室温で乾燥させる。 (JIS C5028/MIL-STD-202 試験法101) 48±4 hours exposure to a salt spray from the 5±1% solution at 35±2 °C (JIS C5028/MIL-STD-202 Method 101)	外観 Appearance	異常なきこと No Damage
			接触抵抗 Contact Resistance	40 milliohm MAX.
4-3-10	亜硫酸ガス SO ₂ Gas	コネクタを嵌合させ、40±2 °Cにて 50±5ppm の亜硫酸ガス中に 24時間 放置する。 24 hours exposure to 50±5ppm. SO ₂ gas at 40±2 °C.	外観 Appearance	異常なきこと No Damage
			接触抵抗 Contact Resistance	40 milliohm MAX.
4-3-11	耐アンモニア性 NH ₃ Gas	コネクタを嵌合させ、濃度 28 %の アンモニア水を入れた容器中に 40分間 放置する。 (1L に対して 25mL の割合) 40 minutes exposure to NH ₃ gas evaporating from 28 % Ammonia solution.	外観 Appearance	異常なきこと No Damage
			接触抵抗 Contact Resistance	40 milliohm MAX.

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SHEET

8 OF 12



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項目 Item		条件 Test Condition	規格 Requirement	
4-3-12	半田付け性 Solder-ability	端子先端より0.5mm迄、及び金具先端を 245±3 °C の半田に2～3秒 浸す。 Soldering Time: 2～3 second Solder Temperature: 245±3 °C 0.5mm from terminal tip and fitting nail tip.	濡れ性 Solder Wetting	浸漬面積の 95% 以上 95% of immersed area must show no voids, pin holes
4-3-13	半田耐熱性 Resistance to Soldering Heat	(リフロー時) <u>Refer soldering method</u> 第6項参照 Refer to paragraph 6	端子ガタ、 割れ等 異状なきこと No Damage	
		(手半田) <u>Soldering iron method</u> 端子先端より0.5mm迄、及び金具先端を、370～400 °C の半田ゴテにて、3±1秒加熱する。 Soldering Time: 3±1 second Solder Temperature: 370～400 °C 0.5mm from terminal tip and fitting nail tip		

() : 参考規格 Reference Standard

{ } : 参考単位 Reference Unit

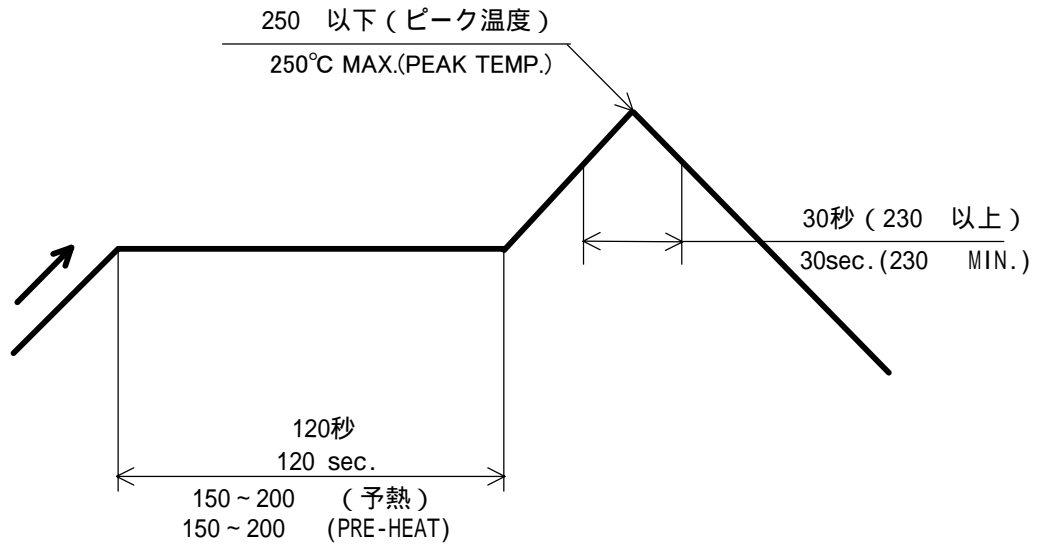
【 5. 外観形状、寸法及び材質 PRODUCT SHAPE, DIMENSIONS AND MATERIALS 】

図面参照 Refer to the drawing.

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		PS-51021-022	PS51021022.lwp	9 OF 12
ES-4000-3996 REV. A SHEET 4 95/MAR/10 EC U5-0926 DCBRD03.LWP				W to B 1 EN-37-1(019)



[6. 赤外線リフロー条件 INFRARED REFLOW CONDITION]



温度条件グラフ
(温度は基板パターン面)

TEMPERATURE CONDITION GRAPH
(TEMPERATURE ON THE SURFACE OF P.C.BOARD PATTERN)

注記;本リフロー条件に関しては、リフロー装置及び基板などにより、
条件が異なりますので、事前にリフロー評価の確認をお願い致します。

NOTE ; Please check the reflow soldering condition by your own devices beforehand.
Because the condition changes by the soldering devices , p.c.boards, and so on.

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SHEET 10 OF 12		
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[7. 挿入力び抜去力 INSERTION/WITHDRAWAL FORCE]

極数 No. of CKT	単位 UNIT	挿入力 (最大値) Insertion (MAX.)			抜去力 (最小値) Withdrawal (MIN.)		
		初回 1st	6回目 6th	30回目 30th	初回 1st	6回目 6th	30回目 30th
2	N {kgf}	19.6 {2.0}	17.6 {1.8}	15.6 {1.6}	2.8 {0.28}	2.3 {0.23}	1.8 {0.18}
3	N {kgf}	24.5 {2.5}	22.5 {2.3}	20.5 {2.1}	3.0 {0.30}	2.5 {0.25}	2.0 {0.20}
4	N {kgf}	29.4 {3.0}	27.4 {2.8}	25.4 {2.6}	3.3 {0.33}	2.8 {0.28}	2.3 {0.23}
5	N {kgf}	34.3 {3.5}	32.3 {3.3}	30.3 {3.1}	3.8 {0.38}	3.3 {0.33}	2.8 {0.28}
6	N {kgf}	39.2 {4.0}	37.2 {3.8}	35.2 {3.6}	4.3 {0.43}	3.8 {0.38}	3.3 {0.33}
7	N {kgf}	44.1 {4.5}	42.1 {4.3}	40.1 {4.1}	4.7 {0.48}	4.3 {0.43}	3.8 {0.38}
8	N {kgf}	49.0 {5.0}	47.0 {4.8}	45.0 {4.6}	5.2 {0.53}	4.7 {0.48}	4.3 {0.43}
9	N {kgf}	53.9 {5.5}	51.9 {5.3}	49.9 {5.1}	5.5 {0.56}	5.0 {0.51}	4.5 {0.46}
10	N {kgf}	58.8 {6.0}	56.8 {5.8}	54.8 {5.6}	5.8 {0.59}	5.3 {0.54}	4.8 {0.49}
11	N {kgf}	63.7 {6.5}	61.7 {6.3}	59.7 {6.1}	6.1 {0.62}	5.6 {0.57}	5.1 {0.52}
12	N {kgf}	68.6 {7.0}	66.6 {6.8}	64.6 {6.6}	6.4 {0.65}	5.9 {0.60}	5.4 {0.55}
13	N {kgf}	73.5 {7.5}	71.5 {7.3}	69.5 {7.1}	6.7 {0.68}	6.2 {0.63}	5.7 {0.58}
14	N {kgf}	78.4 {8.0}	76.4 {7.8}	74.4 {7.6}	7.0 {0.71}	6.5 {0.66}	6.0 {0.61}
15	N {kgf}	83.3 {8.5}	81.3 {8.3}	79.3 {8.1}	7.3 {0.74}	6.8 {0.69}	6.3 {0.64}

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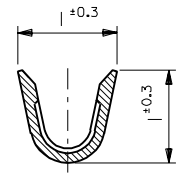
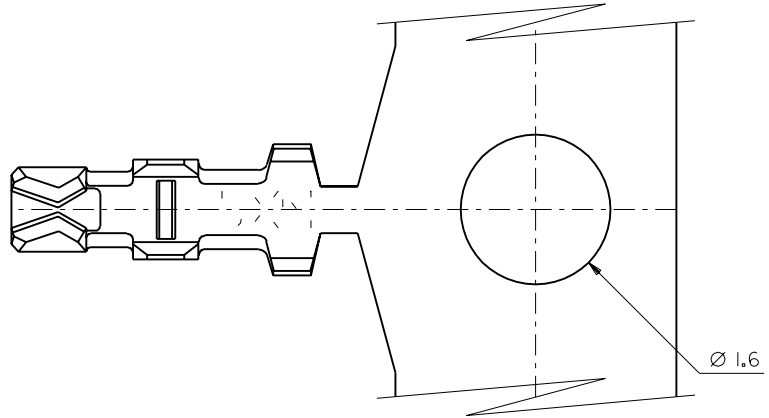
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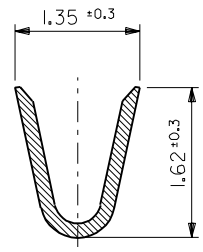
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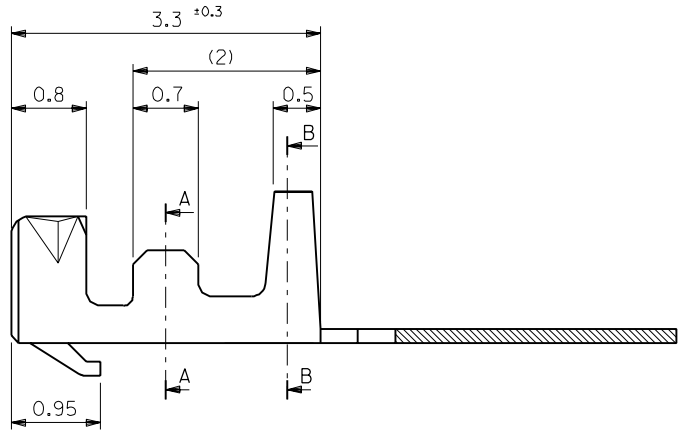
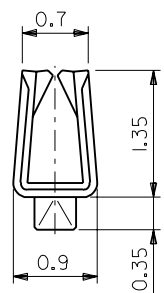
11 OF 12



SECT. A-A



SECT. B-B



50058-8100	バラ状 LOOSE
50058-8000	連鎖状 CHAIN
ENG. NO.	端子形状 FORM

注記
NOTES

- 適合ハウジング：51021シリーズ
APPLICABLE HOUSING：51021 SERIES
- メッキ仕様 PLATING
錫 0.9 μ m MIN. リフロー処理（前メッキ）
TIN 0.9 μ m MIN. REFLOW TREATMENT (PRE-PLATED)

材料 MATERIAL リン青銅 PHOSPHOR BRONZE ($t=0.15$)		仕上げ FINISH —H—	
適用電線範囲 WIRE RANGE AWG #28-32		被覆外径 INS. RANGE $\phi 0.5-1.0$	
DRAWN BY '92/10/21 H.HIRAMOTO		CHK'D BY '93/9/6 M.FUKUSHIMA	
APP'D BY '93/9/6 M.FUKUSHIMA		尺度 SCALE 20 - 1	
角度 ANGLE	$\pm 3^\circ$	記号 LTR	変更内容 REVISION RECORD
30以上 OVER	± 0.3	D	変更 (J30883) REVISED (H.H M.F '93/9/3)
10以上 30未満 OVER UNDER	± 0.25	C	変更&再作図 REVISED & REDRAWN (J20810) (H.H M.F '92/10/27)
10未満 UNDER	± 0.2		
一般公差 GENERAL TOLERANCES		DR. CHK.	日付 DATE

molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
REVISE ONLY ON CAD SYSTEM	
TITLE 名称 1.25 WIRE TO BOARD CONN. CRIMP REC. TERMINAL	
DWG. NO.	REV
SD-50058-8*00	D